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**NATIONAL STANDARD OF THE
PEOPLE'S REPUBLIC OF CHINA**

GB/T 18290.5-2015

Replacing GB/T 18290.5-2000

**Solderless connections -- Part 5: Press-in connections --
General requirements, test methods and practical guidance**

无焊连接 第5部分：压入式连接 一般要求、试验方法和使用导则

(English Translation)

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Foreword

GB/T 18290 "solderless connection" consists of the following components.

- Part 1. solderless connection about connections - General requirements, test methods and practical guidance;
- Part 2. solderless connection crimped connections - General requirements, test methods and practical guidance;
- Part 3. solderless connector solderless accessible insulation displacement connections - General requirements, test methods and guidelines;
- Part 4. solderless connection untouchable solderless insulation displacement connections - General requirements, test methods and guidelines;
- Part 5. solderless connection push-in connections - General requirements, test methods and guidelines;
- Part 6. solderless connector insulation displacement connections - General requirements, test methods and guidelines;
- Part 7. solderless connection spring clamp connections - General requirements, test methods and guidelines;
- Part 8. solderless connection clamping mount connections - General requirements, test methods and practical guidance.

This section GB/T 18290 Part 5.

This section drafted in accordance with GB/T 1.1-2009 given rules.

This Part replaces GB/T 18290.5-2000 "Solderless connections - Part 5. Solderless press-in connections - General requirements, test methods and Guidelines for the use. " Section compared with the GB/T 18290.5-2000, major changes in the following.

- Adds two definitions of "parts" and "sample" (see Chapter 3);
- Amendment plated through hole plated size (see 4.4.3.2);
- Increase the "manufacturer's specification" (see 4.6);
- The "type test" to "test and measurement methods" (see 5.2);
- Added "microscopic cross-section" and "replacement (maintenance)" (see 5.2.2);
- Added "high temperature" test, "Industrial Atmospheric Corrosion" test removed to "Flowing mixed gas corrosion" in place of the test (see 5.2.4);
- The "basic test schedule" and "full test schedule" to "identification test list" and "application test schedule", and Sample preparation was adjusted (see 5.3);
- Added Appendix A.

This section uses the translation method is equivalent to using IEC 60352-5:2003 "solderless connection Part 5. Press - in connections - General requirements, test Methods and practical guidance. " For ease of use, this section made the following editorial changes.

- Remove the imperial units.

Please note that some of the content of this document may involve patents. Release mechanism of the present document does not assume responsibility for the identification of these patents.

This part is proposed by the Ministry of Industry and Information Technology of the People's Republic of China.

This section is under the jurisdiction of the National electronic equipment Electromechanical components for Standardization Technical Committee (SAC/TC166).

This part by the Guizhou Space Appliance Co., Ltd., Shenzhen Electronics Co. Alto, responsible for China Electronics Standardization Institute Drafted.

Introduction

This section includes requirements, tests and practical guidance information, and give two test schedule.

- Identification test schedule. for a single push-in connection (press-in area).

Taking into account the requirements of Chapter 4, provided by the press-in area to the

manufacturer specification test (see 4.6).

Identification of components used in press-in area is independent.

--- Application test schedule. for press-fit connector element portion has passed the test schedule identification.

Test sequence element in the implementation of the assessment is the push-performance connections.

Since the press-in area manufacturer must provide the main content of the required identification, so throughout this section referred to as "factory." IEC Guide 109.1995 to promote products to reduce the impact on the natural environment in the product life cycle. This section of the timber to allow some the material used may have a negative impact on the environment. In order to guide technically replace these materials, which will disappear in this section.

Solderless connections - Part 5. Press - in connections General requirements, test methods and practical guidance

1 Scope and purpose

GB/T 18290 apply to this part of solderless press-in connection, this connection is used for communications equipment and electronic devices employing similar techniques.

Preparation of.

Press-fit connection with the embedded double-sided or multilayer PCB plated through-hole press-fit terminations.

Further, in order to obtain a stable electrical connection under specified environmental conditions, in addition to the test procedure, this section also provides for the use from industrial solid Some international experience data departure.

The purpose of this section is to determine the suitability of press-fit connections under specified mechanical, electrical and atmospheric conditions.

Only in this section is pressed into the flexible regions were identified.

The use of solid press-in area of \u200b\u200bthe information given in Appendix A.

2 Normative references

The following documents for the application of this document is essential. For dated references, only the dated version suitable for use herein Member. For undated references, the latest edition (including any amendments) applies to this document.

GB/T 2421.1-2008 Environmental testing for electric and electronic products overview and

guidance (IEC 60068-1. 1988, IDT) GB/T 4210-2001 Electrotechnical terminology
 Electromechanical components for electronic equipment [idt IEC 60050 (581). 1978] GB/T
 5095.1-1997 electronic equipment - Basic testing procedures and measuring methods -
 Electromechanical components - Part 1. General (idt IEC 60512-1:1994) GB/T 5095.2-1997
 electronic equipment - Basic testing procedures and measuring methods -
 Electromechanical components - Part 2. General examination, electrical Continuity and
 contact resistance tests, insulation tests and voltage stress test (idt IEC 60512-2. 1985)
 GB/T 5095.4-1997 electronic equipment - Basic testing procedures and measuring
 methods - Electromechanical components - Part 4. Dynamic stress test Test (idt IEC
 60512.4. 1976) GB/T 5095.6-1997 Electromechanical components for electronic equipment
 - Basic testing procedures and measuring methods - Part 6. Climatic tests and Soldering
 tests (idt IEC 60512.6. 1984) GB/T 5095.11-1997 electronic equipment - Basic testing
 procedures and measuring methods - Electromechanical components - Part 11. Climatic
 tests (Idt IEC 60512.11-1:1995, idt IEC 60512.11-7:1996, idt IEC 60512.11-8:1995) IEC
 60249-2-4. 1987 printed circuit substrates - Part 2. Specifications Specification 4. General
 Purpose copper clad epoxy glass cloth laminated board
 (Basematerialsforprintedcircuits-Part 2. Specifications-SpecificationNO.4.
 Epoxidewovenglass fabriccopper-cladlaminatedsheet, generalpurposegrade) Amendments
 3 (1993) (Amendment3) IEC 60249-2-5. 1987 printed circuit substrates - Part 2.
 Specifications Specification 5. Flame retardant epoxy glass cloth copper clad laminate
 (vertical Direct burning test) [Basematerialsforprintedcircuits-Part 2.
 Specifications-SpecificationNO.5. Epoxide
 wovenglassfabriccopper-cladlaminatedsheetofdefinedflammability (verticalburningtest)]
 Amendments 3 (1993) (Amendment3) Amendments 4 (1994) (Amendment4) IEC
 60249-2-11. 1987 general-purpose thin copper clad epoxy glass cloth laminate
 (manufactured multilayer printed boards) (Basemate-